



Material Content Data Sheet



Sales Product Name		IPC50N04S5-5R8		Issued		24. January 2018		
MA#		MA001328710						
Package		PG-TDSON-8-33		Weight*		111.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.285	0.26	0.26	2559	2559
leadframe	non noble metal	iron	7439-89-6	0.053	0.05		479	
	inorganic material	phosphorus	7723-14-0	0.016	0.01		144	
	non noble metal	copper	7440-50-8	53.151	47.79	47.85	478072	478698
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	410	410
encapsulation	organic material	carbon black	1333-86-4	0.077	0.07		693	
	plastics	epoxy resin	-	6.089	5.48		54763	
	inorganic material	silicondioxide	60676-86-0	32.369	29.11	34.66	291147	346603
leadfinish	non noble metal	tin	7440-31-5	1.574	1.42	1.42	14156	14156
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1882	1882
solder	noble metal	silver	7440-22-4	0.012	0.01		103	
	non noble metal	tin	7440-31-5	0.009	0.01		83	
	non noble metal	lead	7439-92-1	0.440	0.40	0.42	3953	4139
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		1	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0
heat sink CLIP	non noble metal	iron	7439-89-6	0.017	0.02		152	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	copper	7440-50-8	16.828	15.14	15.16	151356	151553
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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